

# **Description**

The HXY20N10D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



TO252-2L

#### **General Features**

 $V_{DS} = 100V I_{D} = 20A$ 

 $R_{DS(ON)}$  < 87 m $\Omega$  @  $V_{GS}$ =10V

# **Application**

Battery protection

Load switch

Uninterruptible power supply

# PIN1 G PIN3 S

N-Channel MOSFET

## **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
HXY20N10D	TO252-2L	20N10 XXX YYYY	2500

### Absolute Maximum Ratings Tc=25°C unless otherwise noted

Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	V		
Vgs	Gate-Source Voltage	±20	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	20	Α	
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10	Α	
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	5	Α	
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3.4	Α	
Ідм	Pulsed Drain Current <sup>2</sup>	30	Α	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	6.1	mJ	
las	Avalanche Current	15	Α	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup> 34.7		W	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	2	W	
Тѕтс	Storage Temperature Range	-55 to 150	°C	
TJ	Operating Junction Temperature Range -55 to 150		°C	
Reja	Thermal Resistance Junction-ambient <sup>1</sup> 62		°C/W	
R <sub>θ</sub> JC	Thermal Resistance Junction-Case <sup>1</sup> 3.6		°C/W	



# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V
$\triangle BV_{DSS}/\triangle T$	BVDSS Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA		0.098		V/°C
D	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =10A		80	87	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance-	V <sub>GS</sub> =4.5V , I <sub>D</sub> =8A		95	105	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.0		2.5	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS=VDS , ID =250UA		-4.57		mV/°C
1	Drain-Source Leakage Current	V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	
I <sub>DSS</sub>		V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		13		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2		Ω
$Q_g$	Total Gate Charge (10V)			26.2		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =80V , V <sub>GS</sub> =10V , I <sub>D</sub> =10A		4.6		nC
Q <sub>gd</sub>	Gate-Drain Charge			5.1		
$T_{d(on)}$	Turn-On Delay Time			4.2		
Tr	Rise Time	$V_{DD}$ =50V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		8.2		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =10A		35.6		ns
Tf	Fall Time			9.6		
Ciss	Input Capacitance			1535		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		60		pF
Crss	Reverse Transfer Capacitance			37		

#### **Diode Characteristics**

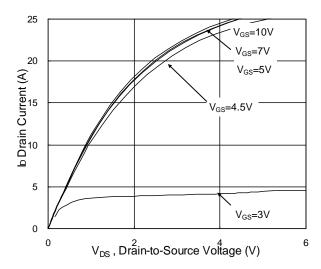
Symbol	Parameter	Conditions		Тур.	Max.	Unit
ls	Continuous Source Current <sup>1,5</sup>	\/0\/ Force Current			20	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>	=V <sub>D</sub> =0V , Force Current			30	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup> V <sub>G</sub>	s=0V , Is=1A , T <sub>J</sub> =25°C			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			37		nS
Q <sub>rr</sub>	Reverse Recovery Charge	=10A , dl/dt=100A/µs , T <sub>J</sub> =25°C		27.3		nC

#### Note

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =11A
- 4. The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

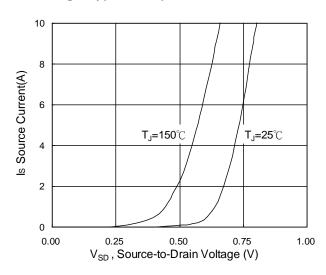


Fig.3 Forward Characteristics Of Reverse

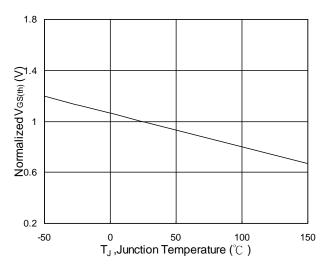


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

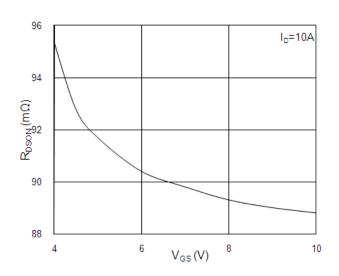


Fig.2 On-Resistance vs. Gate-Source

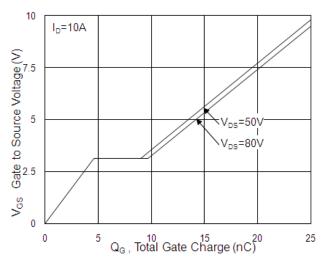


Fig.4 Gate-Charge Characteristics

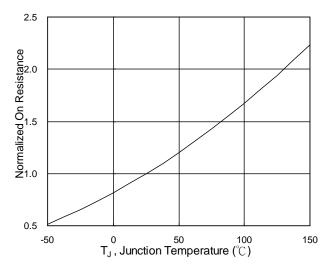
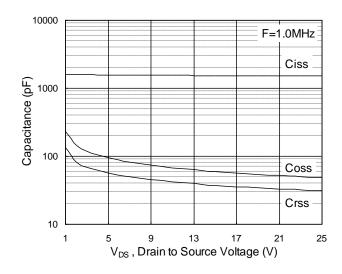


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



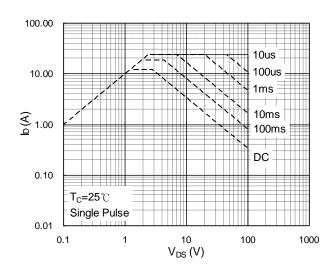


Fig.7 Capacitance

Fig.8 Safe Operating Area

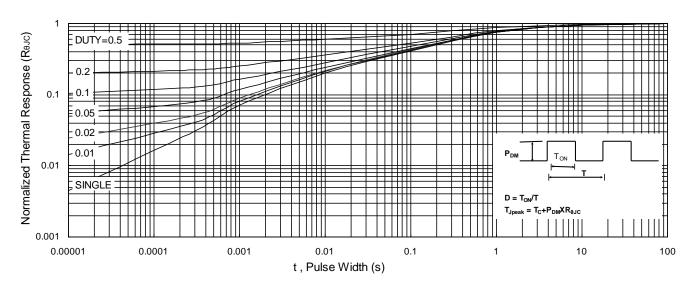
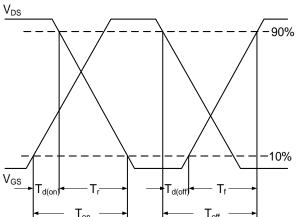


Fig.9 Normalized Maximum Transient Thermal Impedance



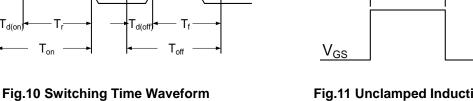


Fig.11 Unclamped Inductive Switching Waveform

 $\mathsf{EAS} = \frac{1}{2} \mathsf{L} \ \mathsf{x} \ \mathsf{I_{AS}}^2 \ \mathsf{x} \frac{\mathsf{BV_{DSS}}}{\mathsf{BV_{DSS}} \cdot \mathsf{V_{DD}}}$ 

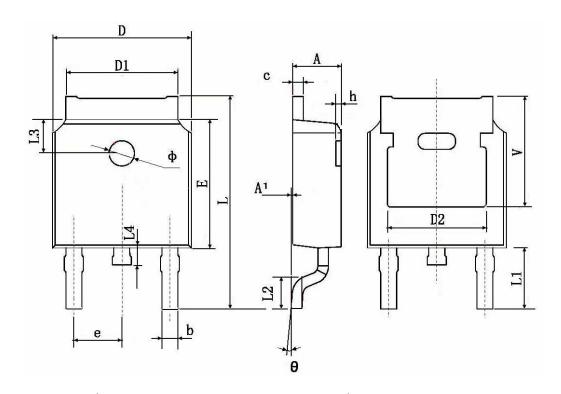
BV<sub>DSS</sub> --

 $I_{AS}$ 

- V<sub>DD</sub>



# **TO-252-2L Package Information**



Comple at	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	TYP.	0.190	TYP.	
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	TYP.	0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600	TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		



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